ABSTRACT OF THE DISCLOSURE

LEAD FRAME, METHOD OF MAKING THE SAME, AND SEMICONDUCTOR DEVICE USING THE SAME

A lead frame for semiconductor device comprises first inner leads 21-2, 21-3 and 21-4 each having a region 22-2, 22-3, 22-4 on which a predetermined quantity of adhesive is applied, and second inner leads 21-1 and 21-5 each having a region 22-1, 22-5 which is wider than those of the first inner leads. The first inner leads 21-2, 21-3 and 21-4 have a width W_1, while the second inner leads 21-1 and 21-5 have a width W_2 which is wider than W1. The second inner leads 21-1 and 21-5 are arranged at the positions where one successive application of varnish-like adhesive to the inner leads begins and ends, respectively. The ratio of W_1 to W_2 is preferably 1 to 1.3 (i.e., $W_1:W_2 = 1:1.3$) or more. Even if an excessive quantity of varnish-like adhesive is applied to the beginning inner lead 21-1 or the ending inner lead 21-5, it is spread over the region 22-1 or 22-5, then adhesive layers having uniform thickness are formed.

THIS SHEET HAS BEEN REPLACED

This Sheet Has Been Replaced

